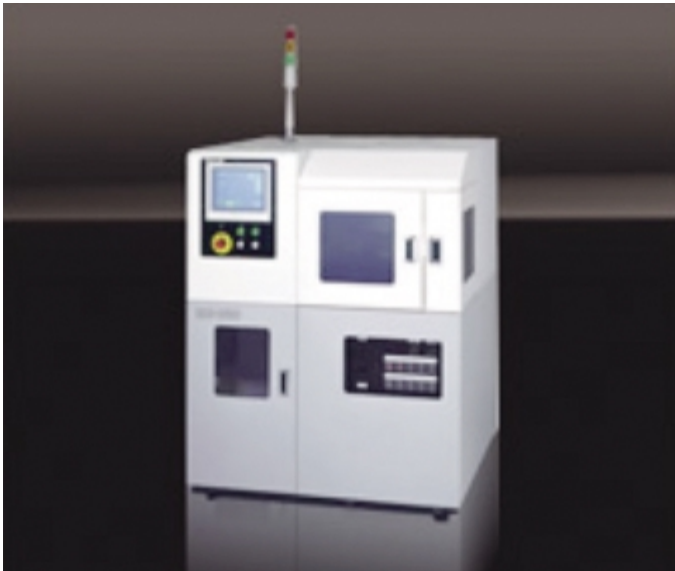


200mm Fully-Automatic BG Tape Remover

RAD-3000F/8



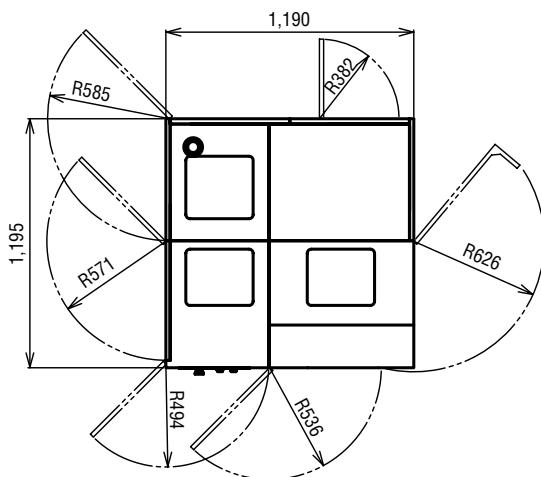
Outline

- Fully-automatic BG Tape remover for single wafer.
- After alignment, UV is irradiated when necessary, and back grinding tape is removed by attaching heat seal on the periphery of the wafer, fixed with heater.

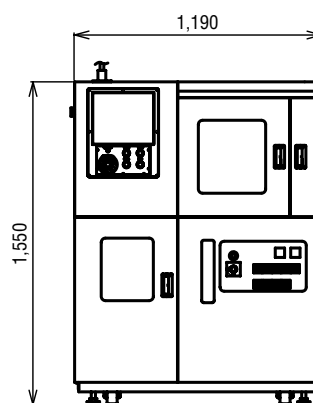
Option ·Host Communication Function (Communication Format :
Conforms to SECS-I and HSMS/Software : Conforms to GEM)

Suitable Tapes ·BG Tape : Adwill E series, P series

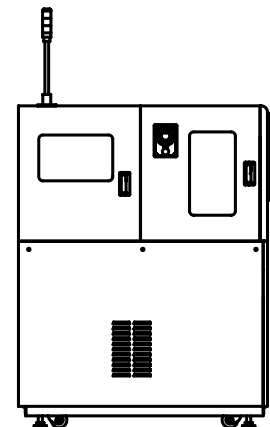
External View



Top View



Front View



Left Side View

Unit:mm

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 5.0kW
Air Supply	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)
Vacuum Supply	Vacuum pressure	: >-80kPa

Applicable Wafer Size 125mm, 150mm, 200mm

Size Width : 1,190mm
Depth : 1,195mm
Height : 1,550mm
(excluding the signal tower)

Weight 1,000kg

UPH 80wafers/hour

The above processing capacity is based on following conditions:

Wafer : 200mm diameter non-polished mirror wafer
Back grinding tape : E-6142S from LINTEC



LINTEC Corporation *Linking your dreams*

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